

NOTES:

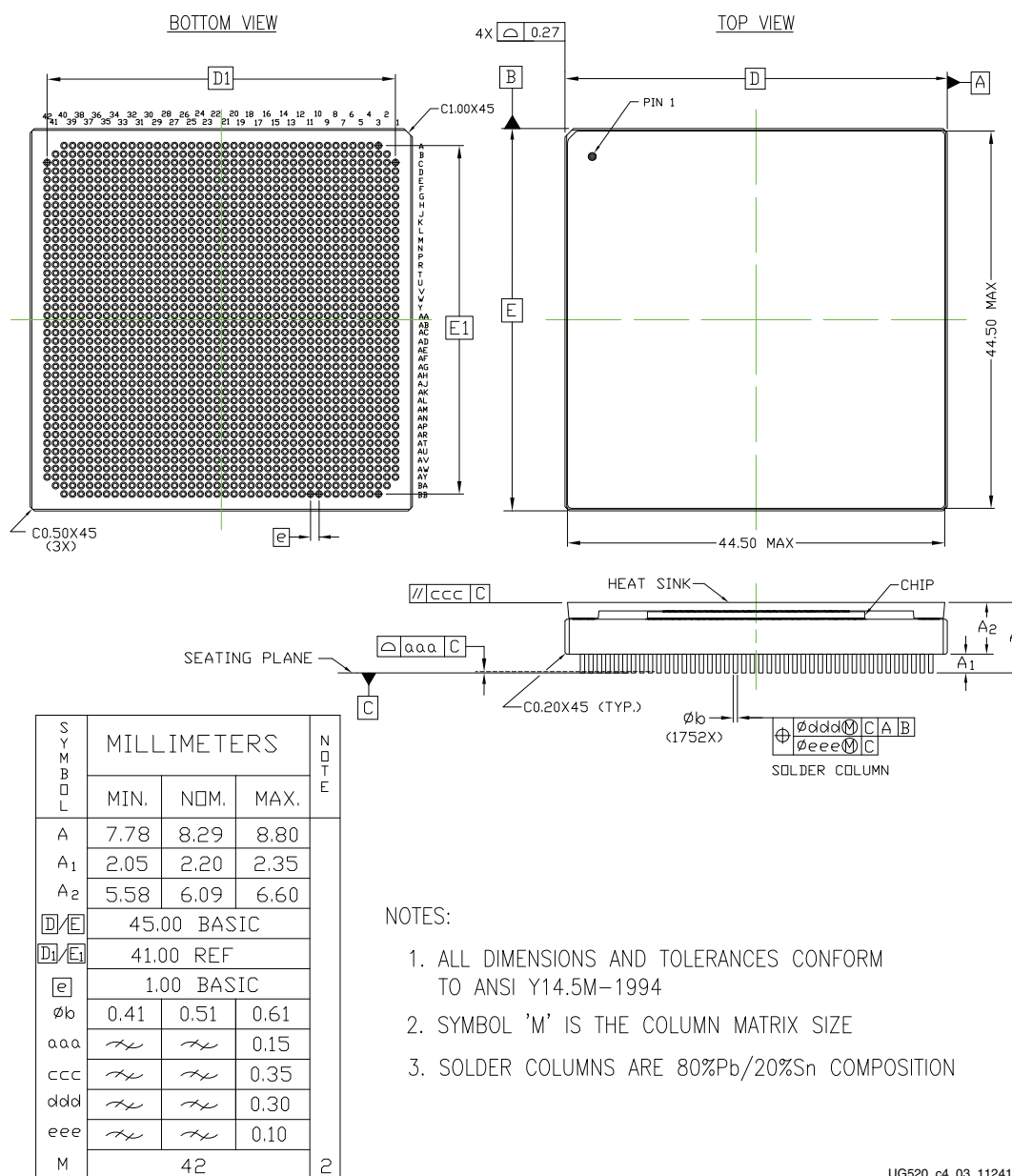
1. THIS PAGE IS TO SHOW THE OPTIONAL LID AND CHIP CAP LOCATIONS.
2. ALL DIMENSIONS ARE THE SAME EXCEPT FOR THE LID.
3. CHIP CAPS: ACCEPTS 0603 (25 PLCS) AND 0805 (6 PLCS)
4. CHIP CAP REFERENCE:
  - (A) – VCCAUX
  - (B) – VCCINT
  - (CN) – VCCO\_[1~29] ("N" CORRESPONDS TO BANK NUMBER)
5. CAP PLACEMENT AND QUANTITIES REMAIN THE SAME FOR ALL CF AND CN PACKAGES

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**Figure 4-2: CF1752 Ceramic Flip-Chip Column Grid Array Package Mechanical Drawing (32 mm × 25 mm Lid) (This Package is Obsolete per [XCN12020](#))**

# CN1752 Ceramic Flip-Chip Column Grid Array Package Specifications

CN1752  
(WITH SOLDER COLUMNS ATTACHED)



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Figure 4-3: CN1752 Ceramic Flip-Chip Column Grid Array Package Mechanical Drawing (45 mm × 45 mm Lid)

**Note:** The material used for the CN1752 lid is Nickel-plated Al-SiC, which is conductive and NOT connected to ground. For space environments, the Al-SiC lid should be connected to system ground.

## CN1752 Daisy Chain Land Pattern

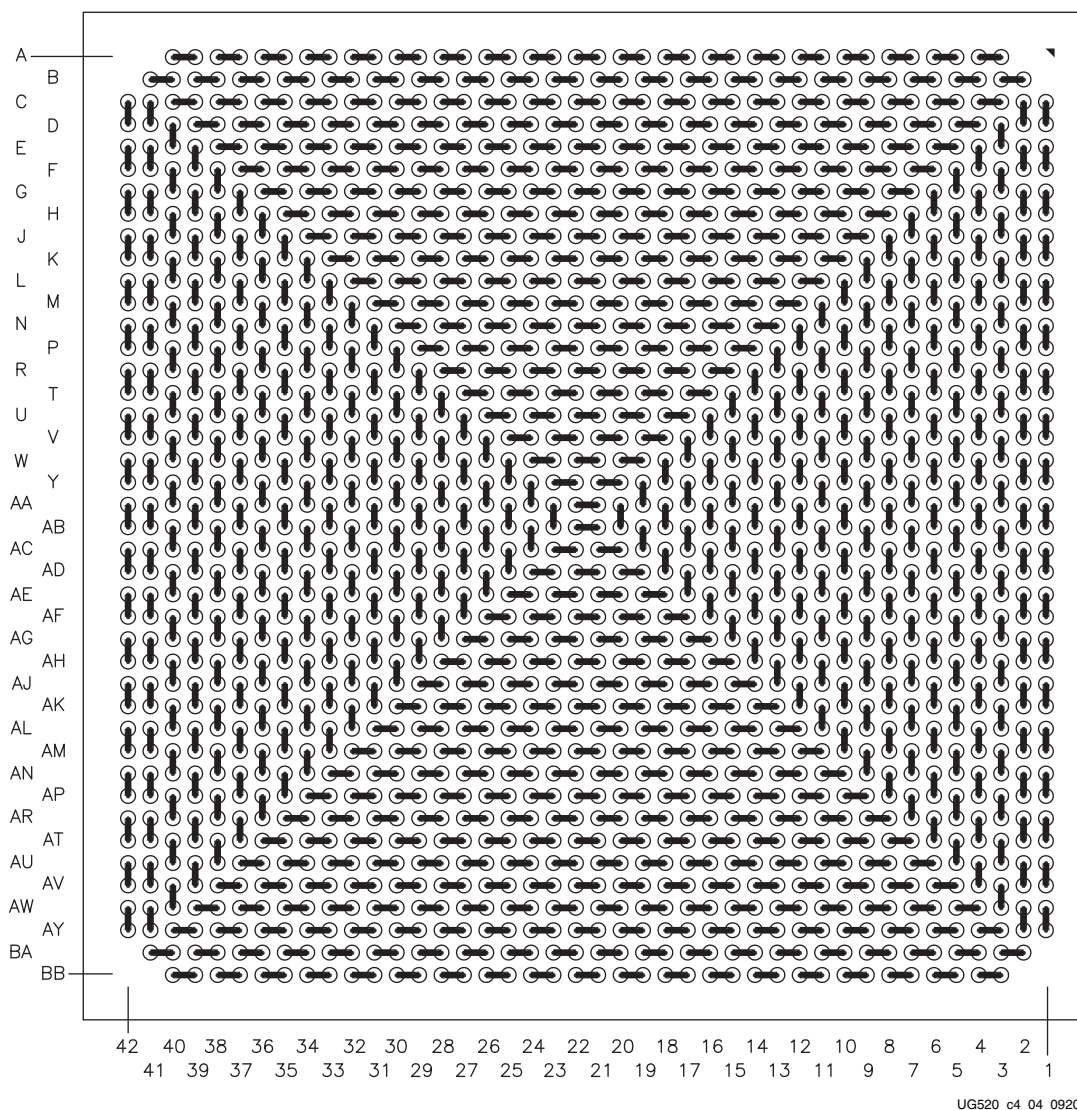


Figure 4-4: CN1752 Daisy Chain Land Pattern